Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **I0206-04** DATE: June 14, 2002
Product Affected: IDT79R3041

Date Effective: September 14, 2002

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ☒ Date Code Top mark will have the character "4" included in the die revision.
- ☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
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Attachment:: ☒ Yes ☐ No

Samples: Available upon request.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☒ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

To consolidate wafer fab production from Salinas, California (Fab 2) to Hillsboro, Oregon (Fab 4), IDT79R3041 will be transferred to IDT's wafer fab facility in Hillsboro, Oregon. There is no change in die technology.

RELIABILITY/QUALIFICATION SUMMARY:

Qualification testing will verify that there is no change to the product reliability. Please see attachment for qualification detail.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY:

DATE:

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: I0206-04

PCN Type: Fab Site Change

Data Sheet Change: None

Detail of Change: Transfer existing qualified product IDT79R3041 from Salinas, California Wafer Fab Facility (Fab 2) to Hillsboro, Oregon Wafer Fab Facility (Fab 4).

Part Number	Salinas Wafer Fab			Hillsboro Wafer Fab		
	Manufacturing Site	Wafer Size	Die Revision	Manufacturing Site	Wafer Size	Die Revision
IDT79R3041	Salinas, CA	6 inch	XG	Hillsboro, OR	8 inch	X4G

Note: There is no change in die technology.

Conversion schedule (Estimated)

Device	Sample Availability	Production Shipments
IDT79R3041	Now	September 14, 2002

ATTACHMENT - PCN #: I0206-04

Qualification Plan: QI02-01

Test Vehicle: IDT79R3041 **Expected Completion Date:** July 26, 2002

	Required Sample/#Fails	Lot #1
Operating Life Test (Dynamic) (1000 Hrs, @125 °C, Vcc = 5.5V)	77/0	
Bake & Ballshear Test @ 200°C / 4 ball bonds per device	5/0	
ESD Human Body Model	3/0	
ESD Charge Device Model	3/0	
Latch up	10/0	
Electrical Characterization	10	

Characterization Data:
Characterization data is available upon request.